

Abstract

An improved method for manufacturing circuit boards which utilizes direct printing methods to form conductor patterns from metal foils disposed on one or both sides of a conventional substrate, to form conductors directly onto a circuit board substrate, to form circuit devices directly onto a circuit board substrate, to form shields directly on circuit patterns, to form solder masks directly on circuit patterns, and to form multilayer circuit board laminates. The circuit devices formed using Applicant's direct printing processes include capacitors, resistors, inductors, and transformers.

09890471-000101